

AT&S

RESULTS FY 2023/24

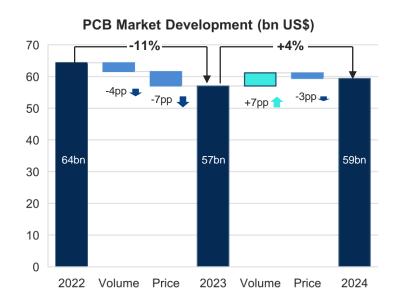
CONFERENCE CALL

MAY 14, 2024

KEY DEVELOPMENTS

- 2023/24 was characterised by a very challenging market environment
 - After solid H1, the market environment deteriorated in H2
 - High inventories of server chips impact IC substrate demand
 - Markets for mobile devices and industrial applications have weakened in H2
- Getting prepared for market recovery and return to growth in FY 2024/25
 - Market recovery still anticipated for the second half of FY 2024/25
 - AT&S volumes expected to increase, but price pressure will remain in place
 - Ramp of plants in Kulim and Leoben on track
- Intensification of cost optimization program including headcount reductions
- Intention to sell the plant in Ansan, Korea
- Proposal to AGM: No dividend for 2023/24
- Medium-term guidance 2026/27 adjusted

PCB MARKET – STABILIZATION AND GROWTH



Challenges:

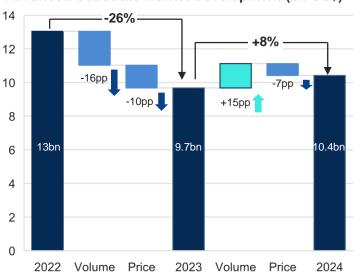
- Geopolitical situation
- Declined demand in the end markets
- Uncertainty among end customers and businesses
- High interest rates
- Downturn: After a record year 2022 the overall PCB market 2023 fell by 11% (-4pp from volume, -7pp from prices)
- Stabilization: From 2024, the PCB market is expected to grow again, by 7% in volume, due to persistent price pressure, value is expect to grow by only 4%
- Growth: Steady demand from end-markets driven by electrification and digitalization are expected to lead to long term growth of 5%

Source: Based on Prismark, February 2024



SUBSTRATE MARKET – SLOWLY RECOVERING

Advanced Substrate Market Development (bn US\$)

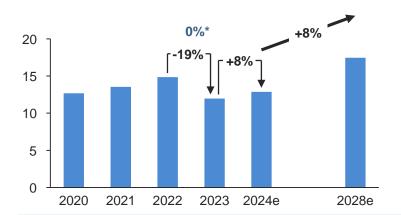


- Volume decline due to end-market weakness and change in system architecture.
 - 26% decline from 2022 to 2024
 - 16pp volume driven 10pp price driven.
- Volume recovery in 2024, but due to price pressure only 8% value growth.
- AT&S on track to become #3 by 2026/27
- AT&S outperformed the market, as volume actually increased
- We have even been able to expand our customer portfolio to include well-known US technology company, also well known customers operating in the Al sector.

Source: Based on Prismark, February 2024

SUBSTRATE END-MARKETS

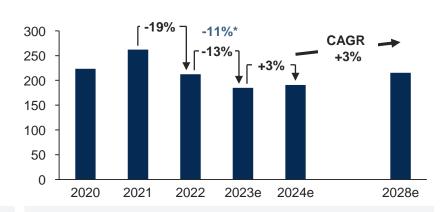
Server shipment [mn units]



- Market recovery expected in 2024. Due to shifted spending patters lower magnitude
- Al emerged as a key driver, but currently high ASPs limiting unit growth
- Cloud spending remains strong

Source: IDC. March 2024

Notebook shipment [mn units]



- Market stopped to decline. Channel inventory normalized
- Slow growth on new normal
- Ordinary seasonal pattern reestablished

Source: IDC, February 2024



New Al Customers for high-end substrates

AMDA

Kulim
AT&S location Malaysia

HTB3
R&D Center Leoben

Optical Modules

for high-speed data transfer in datacenters

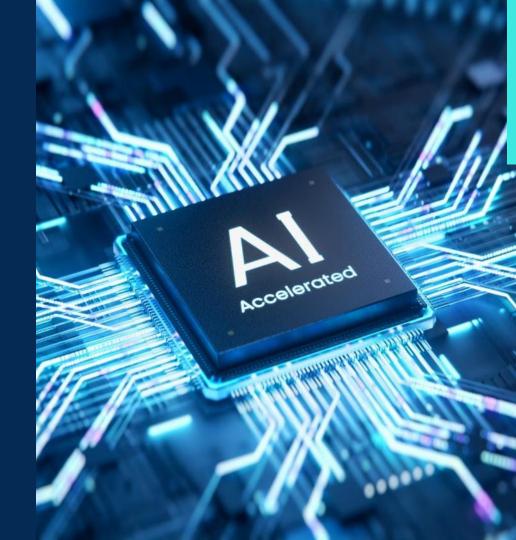
New Power Electronics Solutions

for Datacenter, AI, electric vehicles drive trains

<u> AI – GROWTH</u> **DRIVER FOR** AT&S

Al Training & Al Inference Infrastructure

On-Device-Al



AI TRAINING & AI INFERENCE INFRASTRUCTURE



AT&S delivers solutions for

- Substrates for AI accelerators, CPUs, GPUs
- Packaging technologies for AI power supplies
- Module PCBs for optical transceivers

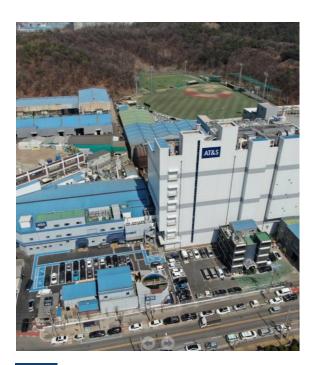
ON-DEVICE-AI



AT&S delivers solutions for

- Smartphones
- Notebooks
- Wearables

INTENTION TO SELL THE PLANT IN ANSAN, KOREA



- Focusses on Thin Flex PCB in medical products with FDA / MDR / IPC
 Class II & III requirements
- Outperforming market growth by offering strong expertise and codevelopment in miniaturization
- Products made in Ansan are essentially different from AT&S's development roadmap
- Provides a fully invested, state-of-the-art production setup
- From a Group perspective 2023/24
 - Revenues: € 76 MM
 - EBITDA: € 38 MM
 - Property, plant and equipment: € 37 MM
- Bidding process initiated and offers expected soon

COST SAVING AND EFFICIENCY PROGRAMS

OPEX program

- € 440 MM saving for FY23/24 and FY24/25 combined
- Achieved saving
- € 440 MM evenly distributed per eight quarters



€ 250 MM savings achieved in FY23/24

Cost saving program intensified to offset price pressure, focusing on sustainable efficiency gain in operation, procurement, SG&A

2024/25 up to **1,000 FTE** in existing locations will be reduced

Kulim and Leoben ICS plant are monitored closely to ensure the ramp up will not be impacted

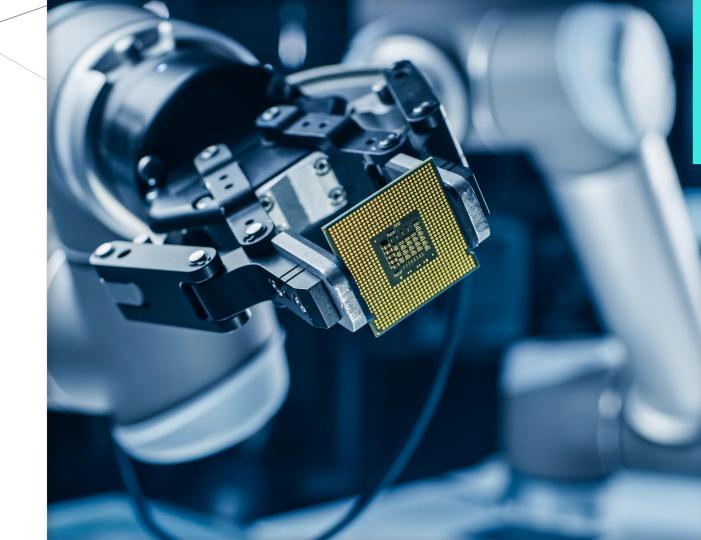
CAPEX program

€ 450 MM reduction, FY23/24 and FY24/25 combined

- Saving on track
- Mainly push-off of CAPEX investment, adjusted to market development

RESULTS FY 2023/24

Petra Preining, CFO



FY 2023/24: RESULTS SUMMARY

Revenue

€ 1,550 MM

- Revenue¹ decreased by 13% -11% without currency effects
- Electronics Solutions: -19%²
- Microelectronics: -2%²

EBITDA

€ 307 MM

- EBITDA¹ decreased by 26% -28% without currency effects
- EBITDA margin: -3.4pp → 19.8%
- Adjusted EBITDA margin: $-1.4 \text{ pp} \rightarrow 24.8\%$

Net profit

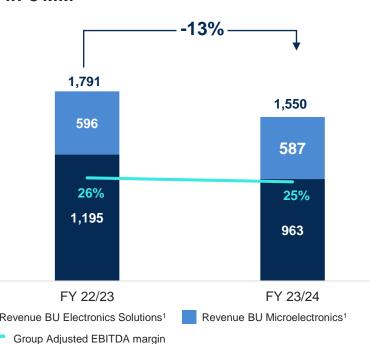
€ -37 MM

- Net profit decreased by 127% -158% without currency effects
- Driven by lower revenue and EBITDA



FY 2023/24: GROUP & BUSINESS UNITS

in € MM



Revenue

Group: Price pressure and negative FX were main burden

BU ES: Unfavorable mix/volume, price pressure and

negative FX weighed on revenue

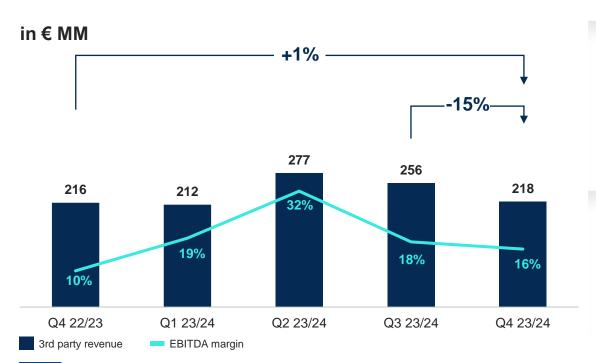
BU ME: Positive product mix/volume compensated by

price pressure

Group margin

Savings effects and mix/volume overcompensated by price pressure

Q4 2023/24 BUSINESS UNIT: ELECTRONICS SOLUTIONS



Revenue

YoY higher by 1%, positive product mix/volume effect compensated by price pressure

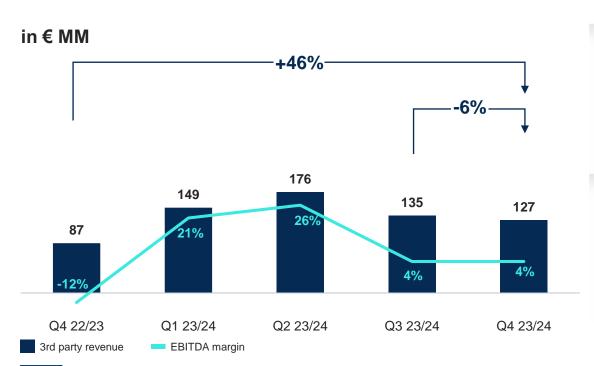
QoQ -15%, due to seasonality of mobile devices and price pressure

Margin

YoY increase due to positive mix/volume effect

QoQ burdened by lower revenue due to seasonality of mobile phones

Q4 2023/24 BUSINESS UNIT: MICROELECTRONICS



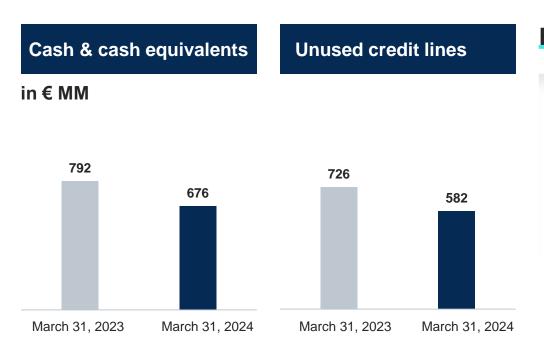
Revenue

YoY +46%, volume growth overcompensating price pressure QoQ -6%, driven by price pressure

Margin

YoY volume increase leads to margin improvement QoQ positive mix/volume effects, but price pressure in place

FY 2023/24 FINANCIAL POSITION



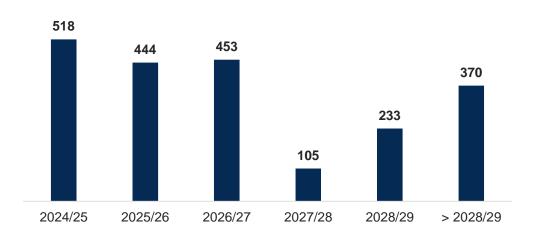
Balancing capital allocation

- Deploying capital with clear approach to invest in strategic growth markets
- Solid financial structure with
 € 1,258 MM cash, cash equivalents
 and unused credit lines
- FX effects on funds impact financial results positively by € 14 MM

DEBT FINANCING OVERVIEW

Maturity of outstanding debt instruments¹

in € MM



- 36% of debt instruments have a fixed interest rate
- Current financing costs of 4.85% (as of Q4 2023/24)

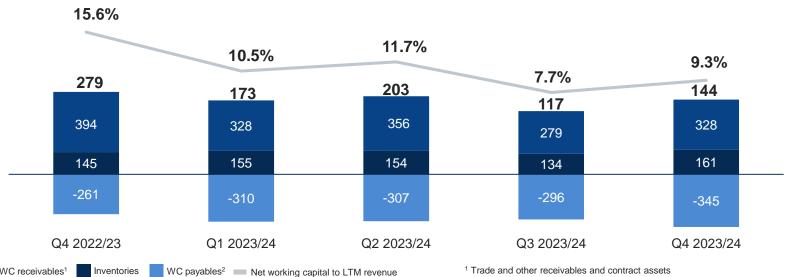
¹ Amounts by maturity as of March 31, 2024. Promissory note loans, term loans with banks, bank borrowings and others; including accrued interest and placement costs and finance leases



HIGH MANAGEMENT FOCUS ON WORKING CAPITAL

Working capital and relation to revenue





¹ Trade and other receivables and contract assets

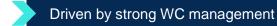
² Trade and other payables and other current provisions, without liabilities from investments

BALANCE SHEET

€MM	Mar. 31, 23	Mar. 31, 24	Change in %	
Total assets	4,162	4,675	+12%	
Equity	1,158	967	-16%	
Equity ratio	27.8%	20.7%	-7.1pp	As anticipated below 30% target
Net debt	851	1,403	+65%	Net debt/EBITDA ratio of 4.6

CASH FLOW

€ MM	FY 22/23	FY 23/24	YoY Change in %
CF from operating activities	476	653	+37%
CF from investing activities	-1,045	-826	+21%
CF from financing activities	211	52	-76%
Operating free CF ¹	-520	-202	+61%
Net CAPEX	996	855	-14%



¹ Cash flow from operating activities minus Net CAPEX



CURRENT YEAR GUIDANCE¹

FY 2024/25			
Revenue	Approx. € 1.7 to 1.8 billion		
Profitability	 Adjusted EBITDA margin of 25–27% Start-up effects of the Kulim and Leoben projects in the amount of approx. € 80 MM 		
Investments	Net CAPEX of up to € 500 million		

¹ Refers to current company structure including plant in Ansan, Korea

MID-TERM GUIDANCE¹

FY 2026/27e – adjusted due to changes in market forecasts			
Growth	Revenue approx. € 3.1 bn (CAGR +26%)		
Profitability	EBITDA margin of 27–32%ROCE of >12% with ramp-up of production		
Others	 Net debt/EBITDA: <3 (can be temporarily exceeded) Equity ratio: ~20% 		

¹ Refers to current company structure including plant in Ansan, Korea

THANK YOU FOR YOUR ATTENTION

AT&S INVESTOR RELATIONS

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